



DO15 GPP Axial-leaded Rectifier

Material Content Declaration					
Material name	Substance name, e.g. Copper (Cu).	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 65.87%	Copper (Cu)	7440-50-8	263.7343	99.9789	658,596.5
	Phosphorus (P)	7723-14-0	0.0026	0.0010	6.5
	Arsenic (As)	7440-38-2	0.0026	0.0010	6.5
	Tin (Sn)	7440-31-5	0.0026	0.0010	6.5
	Oxygen (O)	7782-44-7	0.0013	0.0005	3.2
	Sulfur (S)	7704-34-9	0.0316	0.0120	78.9
	Iron (Fe)	7439-89-6	0.0017	0.0006	4.2
	Nickel (Ni)	7440-02-0	0.0008	0.0003	2.0
	Bismuth (Bi)	7440-69-9	0.0052	0.0020	13.0
	Antimony (Sb)	1309-64-4	0.0052	0.0020	13.0
	Lead (Pb)	7439-92-1	0.0013	0.0005	3.2
	Zinc (Zn)	7440-66-6	0.0008	0.0003	2.0
	Total		263.79		
Solder Wafer 0.60%	Lead (Pb)	7439-92-1	2.155	92.49	5,381.5
	Tin (Sn)	7440-31-5	0.1168	5.01	291.7
	Silver (Ag)	7440-22-4	0.0582	2.50	145.3
	Total		2.33		
Chip 0.83%	Silicon (Si)	7440-21-3	3.17	95.40	7,916.1
	Lead (Pb)	7439-92-1	0.15	4.60	374.6
	Total		3.32		
Molding 32.42%	Silica (SiO ₂)	14808-60-7	94.76	73.00	236,634.4
	Epoxy resin	29690-82-2	22.07	17.00	55,113.1
	Phenolic resin	9003-35-4	11.42	8.80	28,518.0
	Antimony trioxide(Sb ₂ O ₃)	1309-64-4	0.91	0.70	2,272.4
	Brominated epoxy resin	40039-93-8	0.60	0.46	1,498.3
	Carbon Black	1333-86-4	0.05	0.04	124.9
	Total		129.81		
Plating 0.28%	Tin (Sn)	7440-31-5	1.2	100.00	2,996.6
	Total		1.20		
	Total mass (mg)		400.45		